


NOTES:
1) SPECIFIED MANUFACTURERS:
BERGQUIST.
MANUFACTURER MATERIAL SPEC: SP900S

2) MATERIAL SPECIFICATIONS:
- THERMAL CONDUCTIVITY: 1.6 W/m-k OR BETTER.
- OPERATING TEMPERATURES: -25 C TO +125C OR BETTER.
- THERMAL IMPEDANCE: 0.61 C- IN^ 2/W @ 50 PSI OR HIGHER.
- DIELECTRIC BREAKDOWN VOLTAGE (VAC) = 5500.
- FLAME RATING: V - 0

3) SIMILAR TO TENNANT #1201177.

REV-E CHANGES:
1) MOVE THE LEFT MOST 4.75MM HOLE TOWARD THE
CENTER OF THE SIL PAD 2MM. THE DIMENSION 49.28MM
WAS 47.28MM.

PENDING RELEASE

MATERIAL SPECIFICATIONS:		OTHER TREATMENTS AND FINISHES		PAINT - COLOR		MDR: 01/02/2014		X.XX ±0.25 ±[.010]		TO OTHERS WITHOUT WRITTEN PERMISSION OF TENNANT COMPANY.		DWG B SIZE	PART NUMBER 1207443
PART NAME: PAD, SIL, CIRCUITBOARD [T17]				GLOSS	PERFORMANCE	ACCEPTANCE	DES: JOHN HAEG		X.XXX ±0.125 ±[.0049]		<div>SHEET 1 OF 1</div> <div></div>		
								ANGLES ±0.5°					